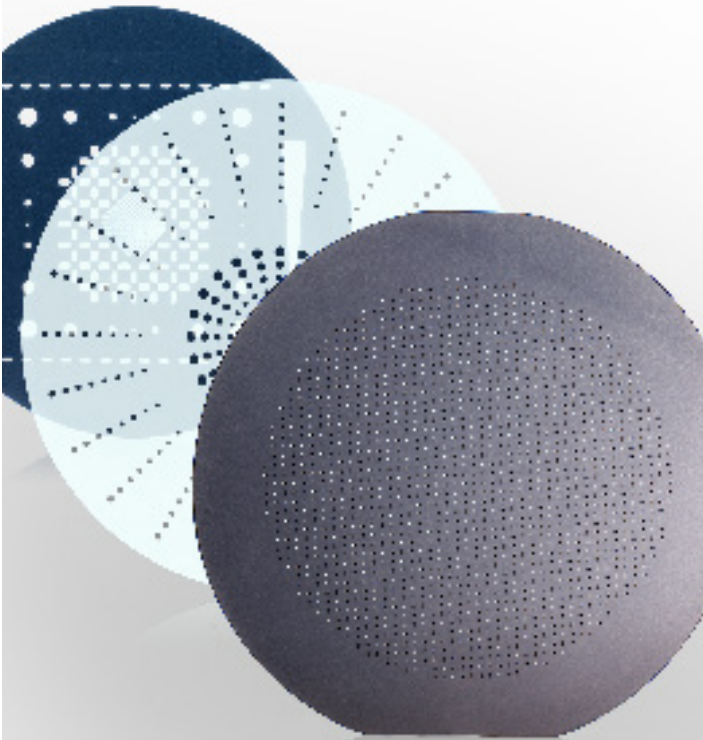




INTRODUCES

# PRECISION ABRASIVE MACHINING



## WAFERS & OTHER BRITTLE MATERIALS

# PRECISION ABRASIVE MACHINING

A state-of-the-art technology for producing a variety of features, shapes and/or perforations in brittle and challenging materials, such as, but not limited to semiconductor wafers, ceramics, sapphire and composites, while ensuring low stress impartation and minimizing compromises to the substrates.

Create fine detailed features and shapes  
(holes, squares, channels, slots, mesa pads, blind vias, etc.)

Dry machining process and no tools to wear out

High degree of accuracy and repeatability  
to within 50µm

Fast turn-around and prototyping for design changes

Precision Abrasive Machining often replaces:  
Ultrasonic machining | CNC drilling | Laser

Just send us your drawing patterns and substrates.

———— We'll do the rest ————

## INDUSTRIES SERVED

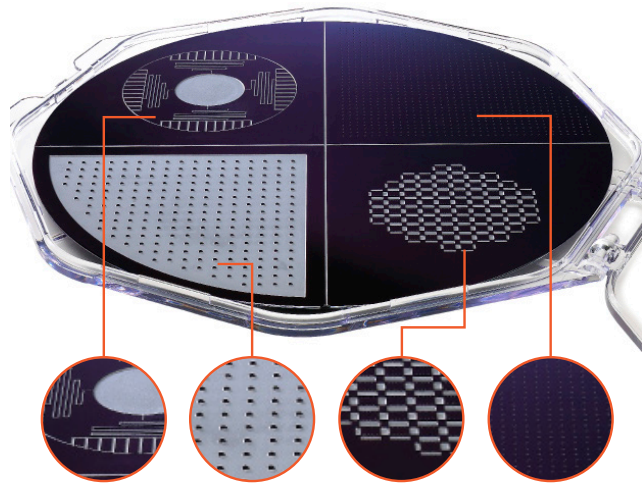
- ▶ MEMS / Sensors
- ▶ Semiconductor
- ▶ Aerospace
- ▶ Biomedical
- ▶ Structural Ceramics

## POTENTIAL APPLICATIONS

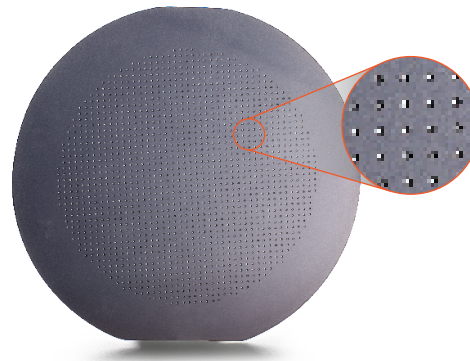
- ▶ Wafer Level Packaging
- ▶ Pressure Sensors
- ▶ Acoustics
- ▶ Bio-MEMS (Lab-On-Chip)
- ▶ Microfluidics

## MATERIALS

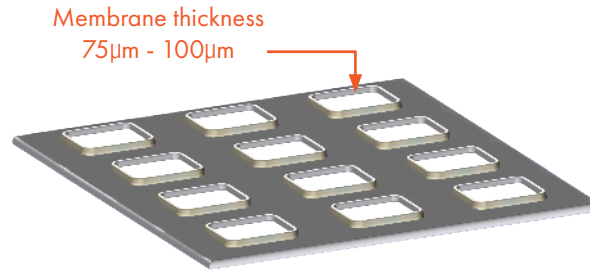
- ▶ Glass, Silicon, Sapphire Wafers
- ▶ Ceramics (Alumina thru Zirconia)
- ▶ Quartz
- ▶ Composites



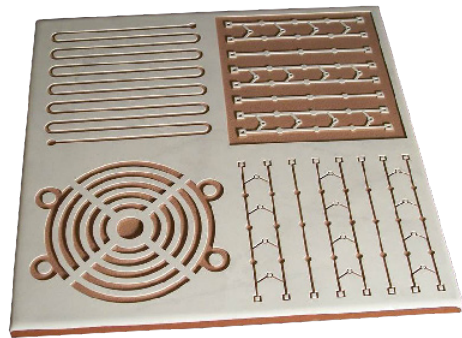
Channels & Slots    Raised Pads/Mesas    Precise Features    Blind vias & Thru-holes



Glass / Quartz / Silicon / Sapphire Wafers with 300µm holes

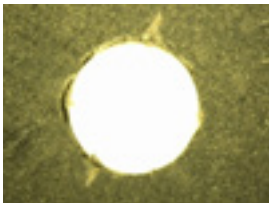


Membrane / Sensor Switches



Ceramic (Alumina, Silicon Carbide, Al nitride, etc.) with any shape features, raised mesas, cavities

Mechanically Drilled



PAM Process



Composite Structure Precision Perforations

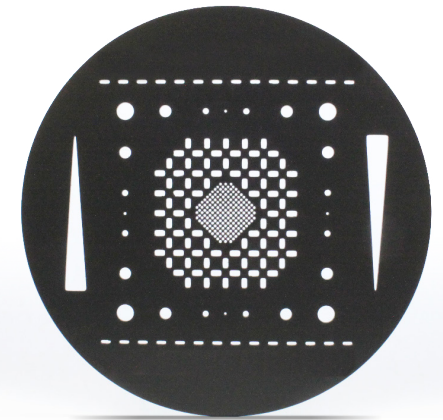


Channels in Graphite

For more information please contact:

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